

MOSFETs Silicon P-Channel MOS (U-MOSVI)

# SSM3J351R

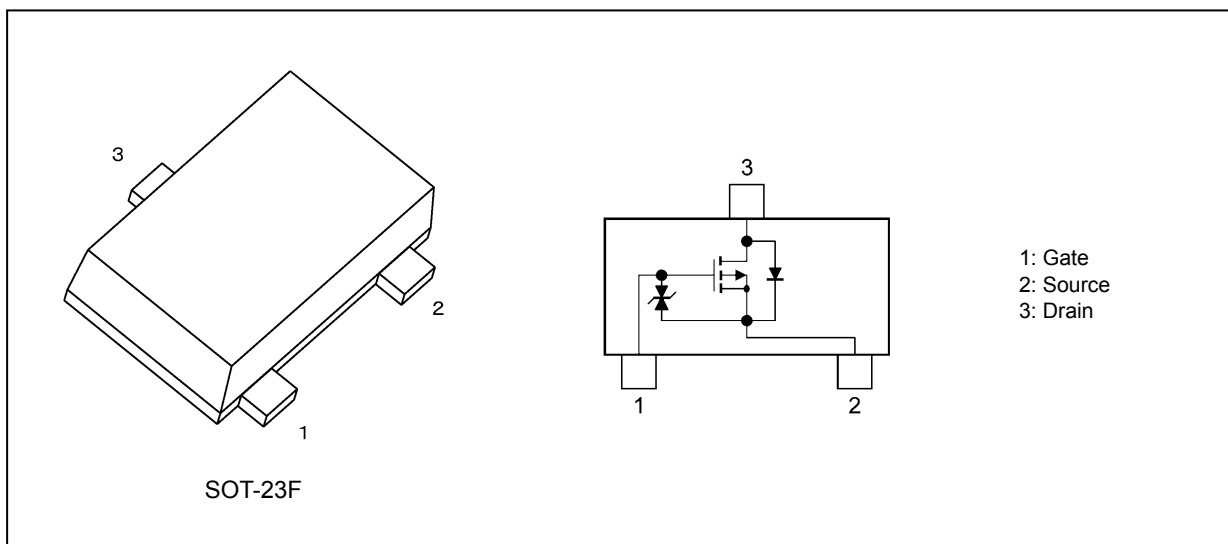
## 1. Applications

- Power Management Switches

## 2. Features

- (1) AEC-Q101 qualified (Please see the orderable part number list)
- (2) 4 V drive
- (3) Low drain-source on-resistance
  - :  $R_{DS(ON)} = 107 \text{ m}\Omega$  (typ.) ( $V_{GS} = -10 \text{ V}$ )
  - $R_{DS(ON)} = 122 \text{ m}\Omega$  (typ.) ( $V_{GS} = -4.5 \text{ V}$ )
  - $R_{DS(ON)} = 129 \text{ m}\Omega$  (typ.) ( $V_{GS} = -4.0 \text{ V}$ )

## 3. Packaging and Internal Circuit



## 4. Orderable part number

| Orderable part number | AEC-Q101     | Note                    |
|-----------------------|--------------|-------------------------|
| SSM3J351R,LF          | —            | General Use             |
| SSM3J351R,LXGF        | YES (Note 1) | Unintended Use (Note 1) |
| SSM3J351R,LXHF        | YES          | Automotive Use          |

Note 1: For more information, please contact our sales or use the inquiry form on our website.

Start of commercial production  
2016-07

### 5. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

| Characteristics                                     | Symbol    | Rating     | Unit             |
|-----------------------------------------------------|-----------|------------|------------------|
| Drain-source voltage                                | $V_{DSS}$ | -60        | V                |
| Gate-source voltage                                 | $V_{GSS}$ | -20/+10    |                  |
| Drain current (DC) (Note 1)                         | $I_D$     | -3.5       | A                |
| Drain current (pulsed) (Note 1), (Note 2)           | $I_{DP}$  | -14        |                  |
| Power dissipation (Note 3)                          | $P_D$     | 1          | W                |
| Power dissipation ( $t \leq 10\text{ s}$ ) (Note 3) | $P_D$     | 2          |                  |
| Single-pulse avalanche energy (Note 4)              | $E_{AS}$  | 8.9        | mJ               |
| Avalanche current                                   | $I_{AR}$  | 3.5        | A                |
| Channel temperature                                 | $T_{ch}$  | 150        | $^\circ\text{C}$ |
| Storage temperature                                 | $T_{stg}$ | -55 to 150 |                  |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Ensure that the channel temperature does not exceed  $150\text{ }^\circ\text{C}$ .

Note 2: Pulse width (PW)  $\leq 1\text{ ms}$ , duty  $\leq 1\%$

Note 3: Device mounted on a  $25.4\text{ mm} \times 25.4\text{ mm} \times 1.6\text{ mm}$  FR4 glass epoxy board (Cu pad:  $645\text{ mm}^2$ )

Note 4:  $V_{DD} = 25\text{ V}$ ,  $T_{ch} = 25\text{ }^\circ\text{C}$  (Initial state),  $L = 1\text{ mH}$ ,  $R_G = 25\ \Omega$

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance,  $R_{th(ch-a)}$ , and the drain power dissipation,  $P_D$ , vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.

### 6. Electrical Characteristics

#### 6.1. Static Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

| Characteristics                         | Symbol        | Test Condition                                            | Min  | Typ. | Max      | Unit             |
|-----------------------------------------|---------------|-----------------------------------------------------------|------|------|----------|------------------|
| Gate leakage current                    | $I_{GSS}$     | $V_{DS} = 0\text{ V}, V_{GS} = -16\text{ V}/+10\text{ V}$ | —    | —    | $\pm 10$ | $\mu\text{A}$    |
| Drain cut-off current                   | $I_{DSS}$     | $V_{DS} = -60\text{ V}, V_{GS} = 0\text{ V}$              | —    | —    | -10      |                  |
| Drain-source breakdown voltage          | $V_{(BR)DSS}$ | $I_D = -1\text{ mA}, V_{GS} = 0\text{ V}$                 | -60  | —    | —        | V                |
| Drain-source breakdown voltage (Note 1) | $V_{(BR)DSX}$ | $I_D = -1\text{ mA}, V_{GS} = 10\text{ V}$                | -50  | —    | —        |                  |
| Gate threshold voltage                  | $V_{th}$      | $V_{DS} = -10\text{ V}, I_D = -1\text{ mA}$               | -0.8 | —    | -2.0     |                  |
| Drain-source on-resistance (Note 2)     | $R_{DS(ON)}$  | $I_D = -1.0\text{ A}, V_{GS} = -4.0\text{ V}$             | —    | 129  | 184      | $\text{m}\Omega$ |
|                                         |               | $I_D = -1.0\text{ A}, V_{GS} = -4.5\text{ V}$             | —    | 122  | 164      |                  |
|                                         |               | $I_D = -1.0\text{ A}, V_{GS} = -10\text{ V}$              | —    | 107  | 134      |                  |
| Forward transfer admittance (Note 2)    | $ Y_{fs} $    | $V_{DS} = -10\text{ V}, I_D = -1.0\text{ A}$              | —    | 6.4  | —        | S                |

Note 1: If a reverse bias is applied between gate and source, this device enters  $V_{(BR)DSX}$  mode. Note that the drain-source breakdown voltage is lowered in this mode.

Note 2: Pulse measurement.

#### 6.2. Dynamic Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

| Characteristics                | Symbol    | Test Condition                                                                                                                                                                                              | Min | Typ. | Max | Unit        |
|--------------------------------|-----------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|------|-----|-------------|
| Input capacitance              | $C_{iss}$ | $V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V},$<br>$f = 1\text{ MHz}$                                                                                                                                         | —   | 660  | —   | $\text{pF}$ |
| Reverse transfer capacitance   | $C_{rss}$ |                                                                                                                                                                                                             | —   | 50   | —   |             |
| Output capacitance             | $C_{oss}$ |                                                                                                                                                                                                             | —   | 70   | —   |             |
| Switching time (turn-on time)  | $t_{on}$  | $V_{DD} = -30\text{ V}, I_D = -1.0\text{ A},$<br>$V_{GS} = 0\text{ to }-4.5\text{ V}, R_G = 10\text{ }\Omega,$<br>Duty $\leq 1\%$ , $V_{IN}$ : $t_r, t_f < 5\text{ ns},$<br>Common source, See Chapter 5.3. | —   | 32   | —   | ns          |
| Switching time (turn-off time) | $t_{off}$ |                                                                                                                                                                                                             | —   | 100  | —   |             |

#### 6.3. Switching Time Test Circuit

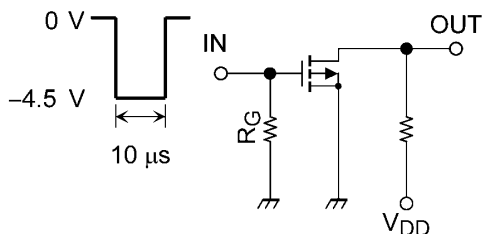


Fig. 6.3.1 Switching Time Test Circuit

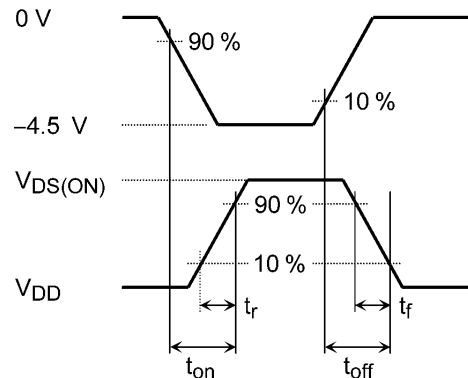


Fig. 6.3.2 Input Waveform/Output Waveform

#### 6.4. Gate Charge Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

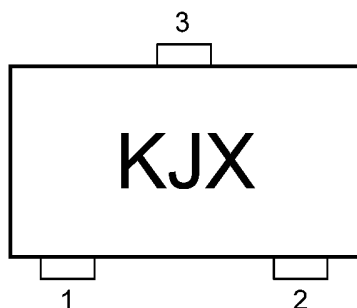
| Characteristics                                 | Symbol    | Test Condition                                                           | Min | Typ. | Max | Unit |
|-------------------------------------------------|-----------|--------------------------------------------------------------------------|-----|------|-----|------|
| Total gate charge (gate-source plus gate-drain) | $Q_g$     | $V_{DD} = -48\text{ V}, I_D = -3.5\text{ A},$<br>$V_{GS} = -10\text{ V}$ | —   | 15.1 | —   | nC   |
| Gate-source charge 1                            | $Q_{gs1}$ |                                                                          | —   | 0.6  | —   |      |
| Gate-drain charge                               | $Q_{gd}$  |                                                                          | —   | 3    | —   |      |

## 6.5. Source-Drain Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

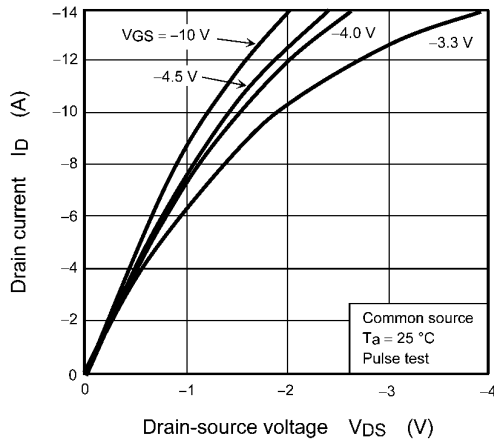
| Characteristics                | Symbol    | Test Condition                               | Min | Typ. | Max | Unit |
|--------------------------------|-----------|----------------------------------------------|-----|------|-----|------|
| Diode forward voltage (Note 1) | $V_{DSF}$ | $I_D = 3.5\text{ A}$ , $V_{GS} = 0\text{ V}$ | —   | 0.85 | 1.2 | V    |

Note 1: Pulse measurement.

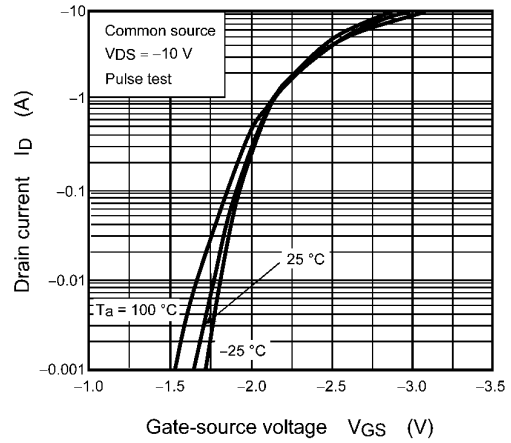
## 7. Marking



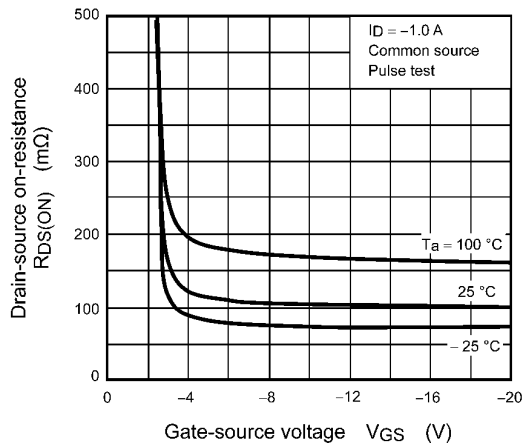
### 8. Characteristics Curves (Note)



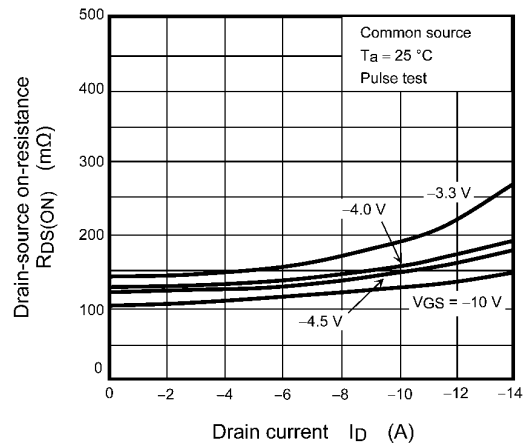
**Fig. 8.1**  $I_D - V_{DS}$



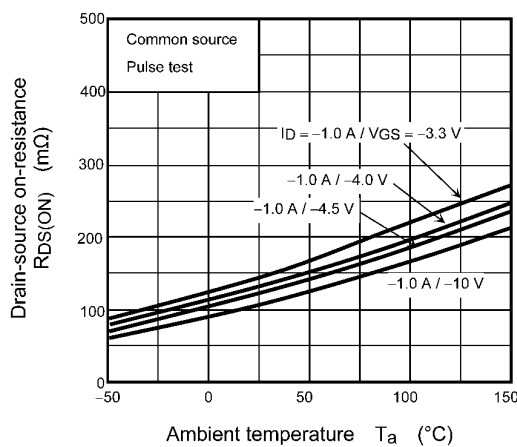
**Fig. 8.2**  $I_D - V_{GS}$



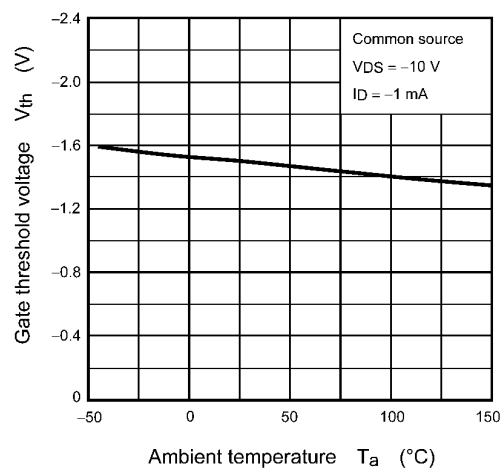
**Fig. 8.3**  $R_{DS(ON)} - V_{GS}$



**Fig. 8.4**  $R_{DS(ON)} - I_D$



**Fig. 8.5**  $R_{DS(ON)} - T_a$



**Fig. 8.6**  $V_{th} - T_a$

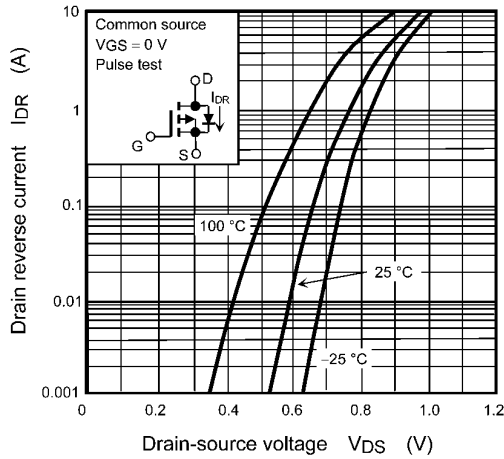


Fig. 8.7  $I_{DR} - V_{DS}$

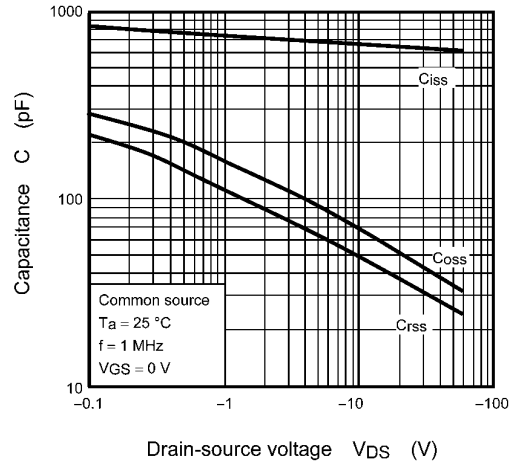


Fig. 8.8  $C - V_{DS}$

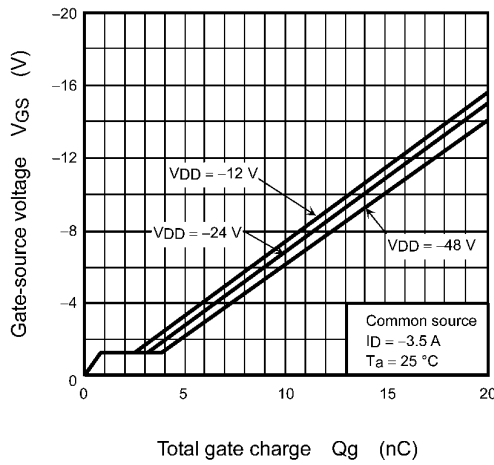


Fig. 8.9 Dynamic Input Characteristics

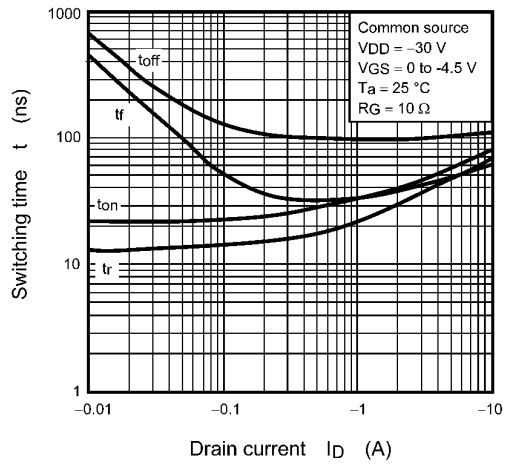


Fig. 8.10  $t - I_D$

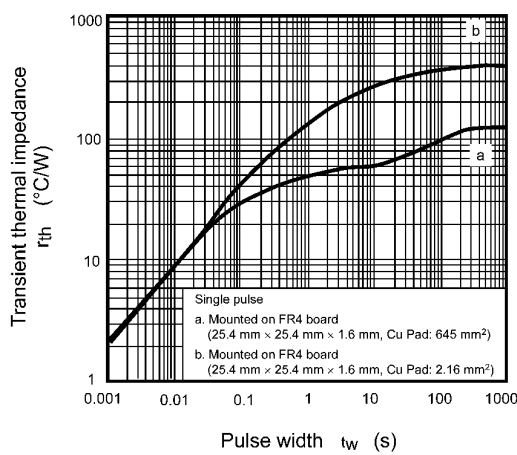


Fig. 8.11  $r_{th} - t_w$

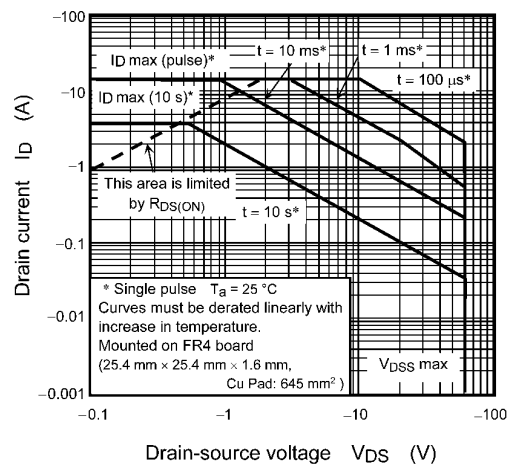


Fig. 8.12 Safe Operating Area

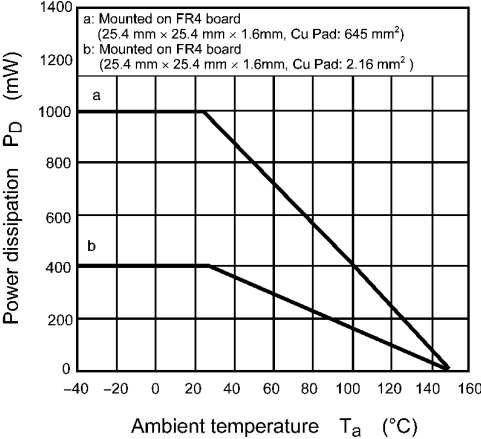


Fig. 8.13  $P_D - T_a$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

## Package Dimensions

Unit: mm



Weight: 0.011 g (typ.)

|                   |
|-------------------|
| Package Name(s)   |
| Nickname: SOT-23F |



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